Investor Update

Jeremy Wang 王志高

Chairman & CEO

Insyde Software Corp. 系微股份有限公司

April, 2026

Safe Harbor Notice

- The statements of its current expectations are forward looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

Agenda

> About Insyde

> Product Portfolio

> Recent Update

> Financial Review

> Q&A

About Insyde®

6231.TWO

Insyde Software

- Founded in 1998 by PCT Chairman Jeremy Wang and SystemSoft EVP Jonathan Joseph
- Business started via acquisition of SystemSoft's BIOS division
- IPO January 23, 2003 (6231.TWO)
- Headquarters: Taipei, Taiwan

#1 BIOS Vendor for Notebooks by Market Share !

Worldwide Presence

- **Headquarter at Taipei, Taiwan**
- Subsidiaries at Massachusetts(USA) and Shanghai (China)
- Representatives in Japan and Europe
- WW Employee numbers : 670+

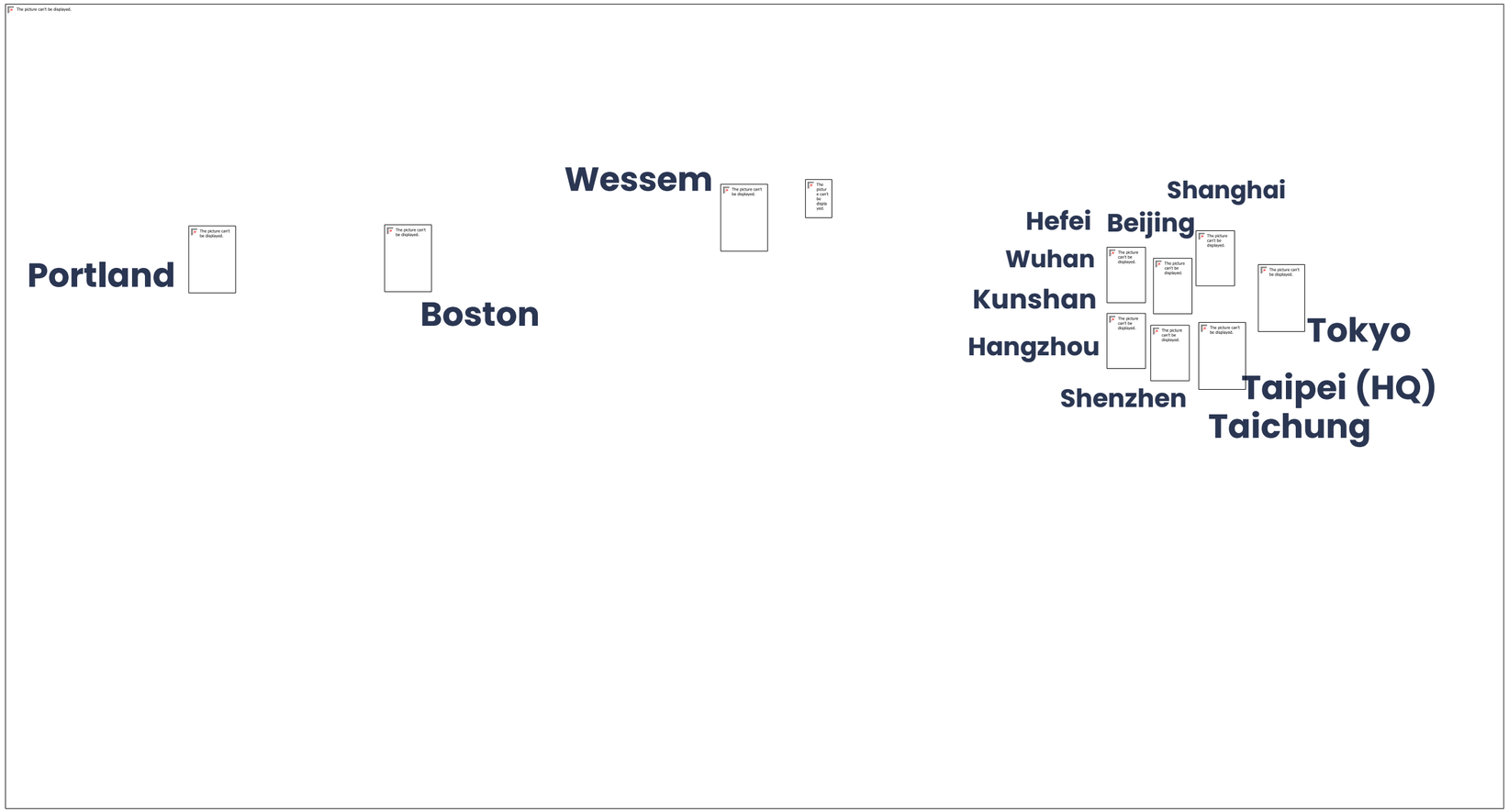
Taiwan

US

China

Japan

Europe

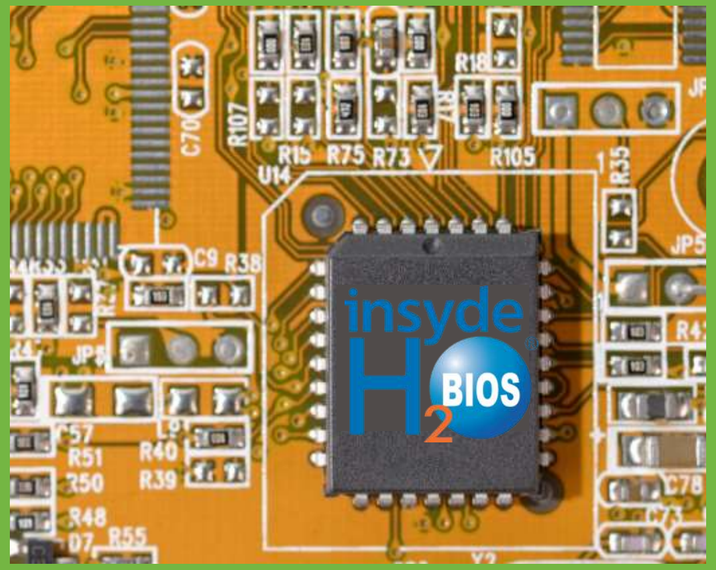


WW Employee numbers : 670+

BIOS – UEFI Firmware

BIOS is stored in the Flash memory and mounted on the motherboard.

- Activated when power button is pushed
- Diagnostic and setup the H/W
- Load and Run OS (ex. Windows/Linux/…)
- Provide services in the background



UEFI Forum

Unified Extensible Firmware Interface Forum

- Original EFI specification developed by Intel, 1999 – 2001
- Specification taken over by non-profit, collaborative trade organization in 2005 – UEFI Forum (http://www.uefi.org)

Insyde is one of the 9 “Initial Promoters”, the only promoter from Taiwan

51 Contributors

Google, NVIDIA, Qualcomm, Broadcom, Oracle, Cisco, Red Hat, Linaro, VMware, Linux Foundation,....., etc.

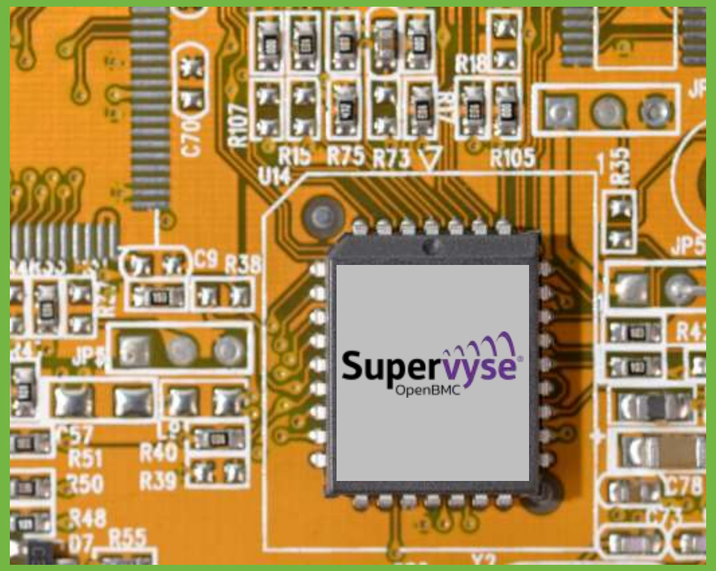
11 Promoters now

AMD, Intel, Microsoft, Dell, HP, IBM, Lenovo, AMI, Insyde, Phoenix, **Apple, ARM**

More than 200 Adopters

BMC – OpenBMC Firmware

OpenBMC is an open-source firmware project used for managing Baseboard Management Controllers (BMCs) in servers, storage, and networking devices. It enables remote monitoring, management, and recovery of systems independent of the main operating system.



OpenBMC

The **OpenBMC community** is an open-source, collaborative group of companies, developers, and Since 2018, it has been a Linux Foundation project, driving open **standards for server management firmware**.
(https://www.openbmc.org/

- Standardizes firmware interfaces using modern technologies like D-Bus and Redfish.
- Encourages open collaboration among hardware vendors (e.g., IBM, Google, Intel, Meta), software engineers, and system integrators.
- Maintains public codebases, documentation, and design discussions through Linux Foundation stewardship, utilizing platforms like GitHub and community mailing lists for collaboration and transparency

OpenBMC

Sine 2022
Insyde was the first IBV to announce the production level of OpenBMC software.

50+ Contributors
Google, Meta, IBM, Microsoft, ARM, Intel, AMD, Aspeed, HPE, Ampere, NVIDIA, Linux Foundation,....., etc.

9 Founding Members
Facebook, Google, IBM, etc.,

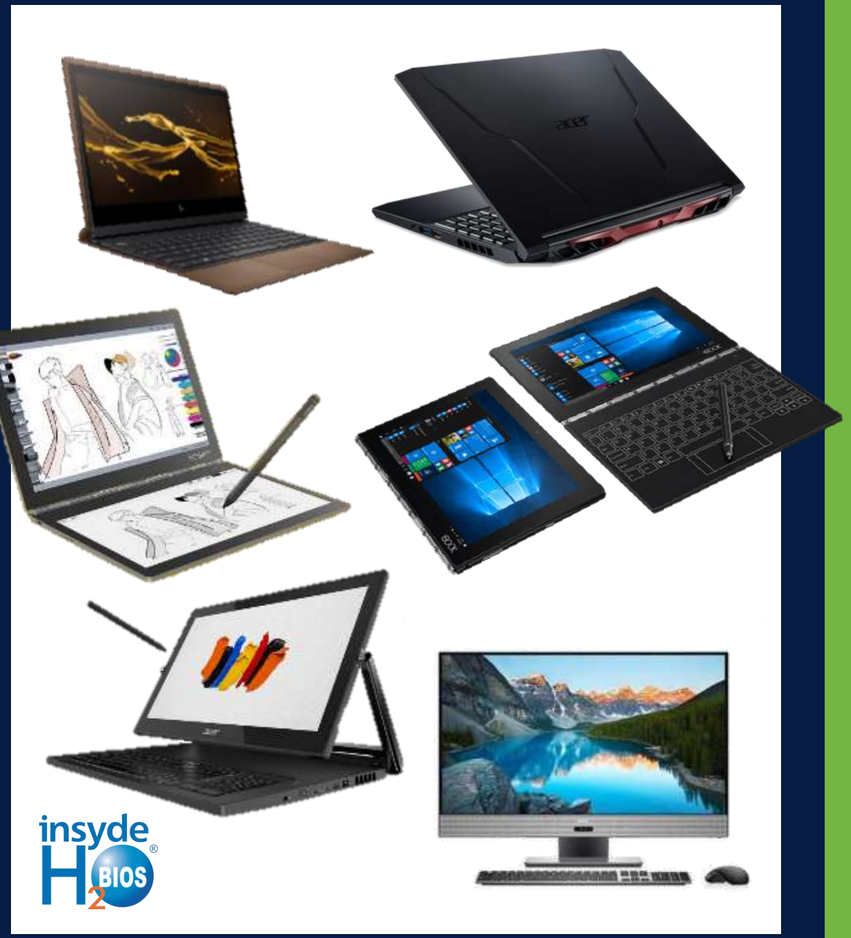
More than 200 Adopters

Product Portfolio

Product market application

Client Computing

Notebook, Tablet, AIO, and Desktop



Server & Storage

Data Center, Enterprise Server Storage, and Networking

Embedded & Edge

POS, Drone, Kiosk, ATM, Robot , Car system..

Accelerate with Insyde

Insyde is helping its customers accelerate the development and adoption of the latest AI-focused technologies and compute platforms

Today's Copilot+ AI PCs Are Powered by InsydeH2O®

insyde H2O BIOS®

Copilot+PC

Firmware for Advanced Server Compute Platforms Designed for Demanding AI & HPC Workloads

insyde H2O BIOS®

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Recent Update

Support for Major Industry Standards

arm SystemReady

CXL Compute Express Link®

DMTF®

DMTF Redfish

FTIA

NIST Security Standards

OpenBMC

OPEN COMMUNITY®

PCI EXPRESS®

THUNDERBOLT™

TRUSTED® COMPUTING GROUP

UEFI

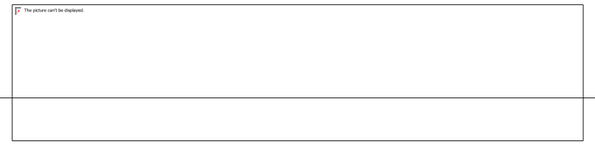
CERTIFIED USB™

Wi Fi™ ALLIANCE

Strong Partnerships with Industry Leaders

arm

ASPEED



BROADCOM

intel

MICROCHIP

MARVELL

Microsoft

NVIDIA

Qualcomm

Trusted Supplier to Leading Companies

Client Computing

acer
ASUS
COMPAL
DELL
FOXCONN
hp
FUJITSU
framework
HONOR
HUAQIN 华勤通讯
英業達 Inventec
Lenovo
LCFC
mi
msi
Microsoft Surface
PEGATRON
廣達電腦 Quanta Computer
wistron

AI, HPC, Data Center

Alibaba.com
Microsoft
HPE
DELL
Atos
FOXCONN
SUPERMICRO
MiTAC
NetApp
COMPAL
WD Western Digital
H3C
flex
GIGA COMPUTING

Networking, IoT & Embedded

ADVANTECH
ERICSSON
CISCO
NEC
ARISTA
SAMSUNG
paloalto NETWORKS
FORTINET
HPE
RICOH
Synology
SIEMENS
JUNIPER NETWORKS
alhua TECHNOLOGY
Accton
Getac
Micron
NCR
Quixant
xerox

Insyde Helps Silicon Vendors and PC OEMs Deliver Leading Edge Products @ CES 2026

50+ designs across 3 silicon vendors and 5 PC OEMs start to ship in Q1'2026

Zenbook/ProArt/Vivobook(WOA)

Aspire/Nitro/Predator/Swift

Yoga Mini i

IdeaPad/Legion/Yoga/ThinkBook/ThinkCentre

HyperX, OmniBook 3/Ultra

XPS/Alienware

MegaBook
2 in 1 Laptop

Note U X1-26-100

WD2-K3

Insyde Supervyse® OPF Ready for ASPEED 8th Generation BMC chips

Next-Gen Silicon Support

First-to-market support for Aspeed's AST2700 (Quad-core, 12nm/28nm) ensures day-one readiness for upcoming server architectures.

Quantum-Ready Security

Industry-leading integration of Caliptra 2.1 Root of Trust and Post-Quantum Cryptography (PQC) algorithms (ML-DSA, L KEM) to meet NIST SP 800-193 standards.

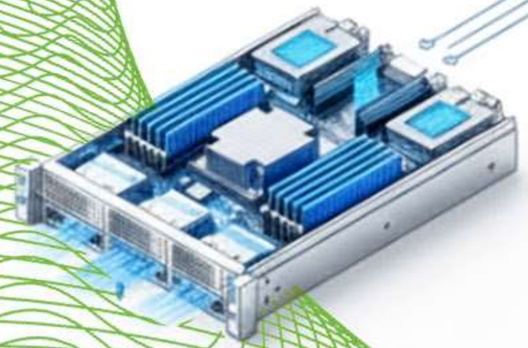
Enhanced Telemetry

Deep hardware-sottware synergy allows for "Anti-Tamper" protection, Voltage Glitch Detection, and real-time intrusion monitoring.

New AI Racks Provide Many Opportunities For Insyde Firmware

CDU Thermal Management
Precision control of CDUs for high- wattage heat dissipation

Intelligent Power Management
Direct management of Power Shelves (PSU/BBU) for peak shaving and load balancing



Compute Trays
Unifying management across heterogeneous silicon.

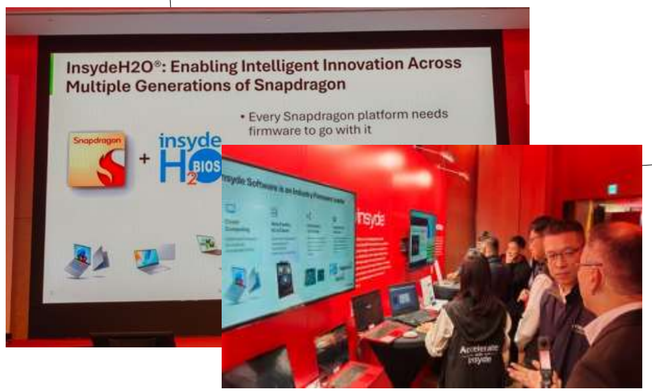
Switch Trays
Seamless integration of High-speed scale out and scale up switches connectivity management.

InsydeH2O® & Supervyse® OPF expands firmware utility beyond the motherboard, acting as the single point of management for the entire AI rack's power, thermal, and compute system.

Recent Industry Events 2025–2026

Snapdragon
Early Access & Boot Camps

2025 Qualcomm Snapdragon Compute Ecosystem Summit in Taipei

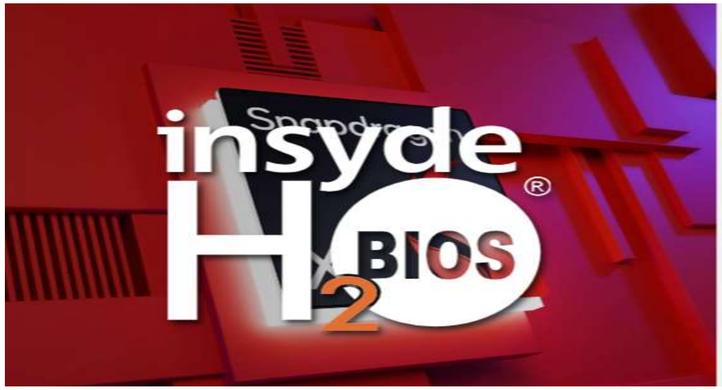


Insyde
Joins First Intel DCDC in India

Insyde Partners with Intel & Senao join MWC Barcelona 2026

Insyde presented on 2/19 Chiplet Summit

PR released 2025 Q4

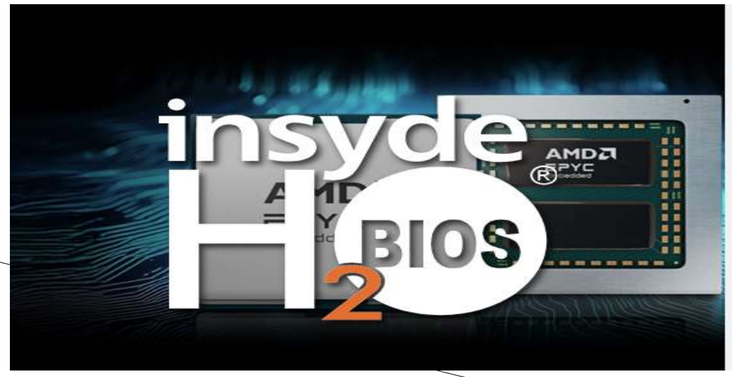


December 29, 2025

Insyde® Software Delivers Industry-First BIOS Debug Solution for PCs with Snapdragon X Series Platforms

H2ODDT™ Pro Unlocks Powerful Debug Capabilities to Accelerate Development of PCs with Snapdragon.

Read the announcement >



December 9, 2025

Insyde Software Ignites Next-Generation Embedded Performance with UEFI BIOS Support for AMD EPYC™ Embedded 2005 Series

InsydeH2O® UEFI BIOS Speeds Deployment of High-performance, Energy-efficient Networking, Storage, and Industrial Systems.

Read the announcement >

November 10, 2025

Insyde® Software Tackles Telemetry of AI Infrastructure at Arm Unlocked Taipei Event

Presentation to Highlight the Importance of Specialized Firmware for Managing AI Infrastructure for Arm Total Design Partners and Others

Read the announcement >

PR released 2025 Q4

November 4, 2025

Insyde® Software Showcases AI-Driven Firmware Leadership at Intel Client PC Ecosystem Symposium 2025

Read the announcement >

October 14, 2025

Insyde® Software Joins Arm Total Design Ecosystem to Drive Server Infrastructure for the AI Era

Custom Firmware, Enabling Tools and Silicon Engagement Program Helps Speed Development of Arm Neoverse CSS Designs

Read the announcement >

October 13, 2025

Insyde® Software Collaboration with Astera Labs' Open Rack Architecture Extends Its OpenBMC Leadership Position

Delivers Proven OpenBMC Systems Manageability for AI Infrastructure 2.0

Read the announcement >

PR released 2025 Q4

October 8, 2025

Insyde Software Drives AI Infrastructure Innovation at the 2025 OCP Global Summit

Leadership Showcased Through Key Industry Partnerships, Technical Presentation and Collaborative Demonstrations

Read the announcement >

Recent Industry Events 2026 Q1

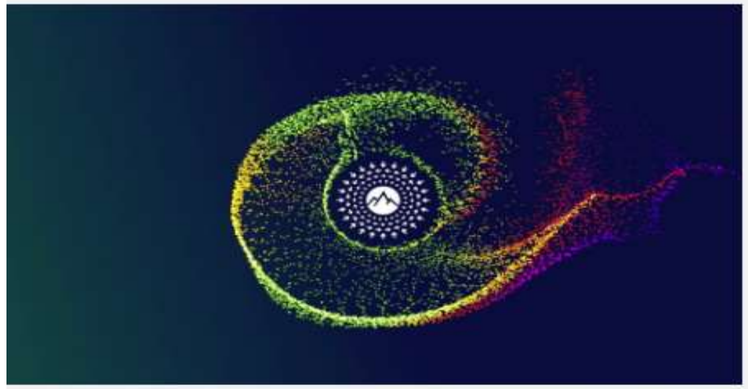
March 10, 2026 - March 12, 2026

Embedded World 2026

Location: Nurnberg Convention Center

View event details >

Recent Industry Events 2026 Q2



2026年04月29日 - 2026年04月30日

OCP EMEA Summit 2026

The **OCP EMEA Summit** serves as a platform where global technical leaders come together to tackle the issues related to data center sustainability, energy efficiency and heat reuse in the region. The focus is on exploring how innovations from hyperscale data center operators can contribute to solving these challenges. The OCP EMEA Summit also highlights deployments of specific OCP-recognized data center equipment in the EMEA region.

Insyde CTO Tim Lewis will be presenting twice during the event:

- **Wednesday, April 29, 14:25PM – 14:40PM**
  - *From Code to Data: Advancing the Unified Platform Configuration Interface (UPCI), with AMI's Felix Polyudov*
- **Thursday, April 30th at 09:55AM**
  - *Shift-Left Firmware Enablement for the Open Chiplet Economy: From Emulation to System-Ready Silicon*, where he will be joined by Vincent Casillas from SiPearl and Ravi Narayanaswami from Cadence

2026年04月13日 - 2026年04月16日

VulnCon 2026

Join Insyde at the 2026 Vulnerability Management Ecosystem Collaboration, Ideation, and Action Conference (VulnCon), co-hosted by FIRST and the CVE Program. The conference will be held April 13–16, 2026, at the DoubleTree Resort by Hilton Hotel Paradise Valley – Scottsdale, Arizona, USA.

On April 13th during the FirmVuln26 workshop, Insyde will deliver two sessions focused on practical firmware security implementation:

- ***Meeting the NSA's Guidance for Managing UEFI Secure Boot*** – Kevin Davis, Security Strategist will examine how evolving threats such as BootHole, BlackLotus, and PKFail have driven a shift from static Secure Boot enablement to active key management and policy enforcement, and how InsydeH2O® enables organizations to operationalize these controls and mitigate persistent firmware threats.
- ***Firmware-Specific Security Guidelines*** – Tim Lewis, CTO will present a focused framework for identifying and mitigating the most common sources of UEFI firmware vulnerabilities, outlining seven high-risk technology areas and actionable coding practices for large-scale firmware development teams.

Read the announcement about Insyde's participation here: https://www.insyde.com/news/press-releases/insyde-software-leads-firmware-security-discussions-at-firmvuln26-workshop-during-vulncon-2026/

VulnCon is open to both FIRST members and non-members worldwide who are actively engaged in the vulnerability management space.

PR released 2026 Q1

March 30, 2026

Insyde® Software Launches TapRUUT™: A Foundational Platform Root of Trust for AI PCs, AI Servers and Next-Gen Data Centers

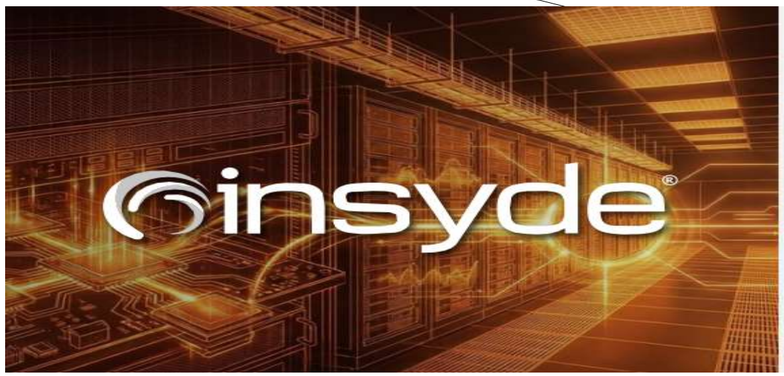
New Product Family Delivers Full NIST SP 800-193 Compliance and Alignment with Future Open Firmware Initiatives

Read the announcement >

March 9, 2026

Insyde® Software Promotes Shift-Left Firmware Design and CRA-Readiness at Embedded World 2026

Read the announcement >



February 10, 2026

Insyde® Software Presents Scalable Telemetry Architecture for Chiplet-Based Platforms at 2026 Chiplet Summit

CTO to Discuss Standards-Based Approach to Enabling Observability from Chip to Data Center

Read the announcement >

PR released 2026 Q2

April 8, 2026

Insyde Software Leads Firmware Security Discussions at FirmVuln26 Workshop During VulnCon 2026

Company's CTO and Security Strategist Present Practical Guidance for Securing UEFI Firmware

Read the announcement >

新聞與活動 - 系微股份有限公司

Financial Review

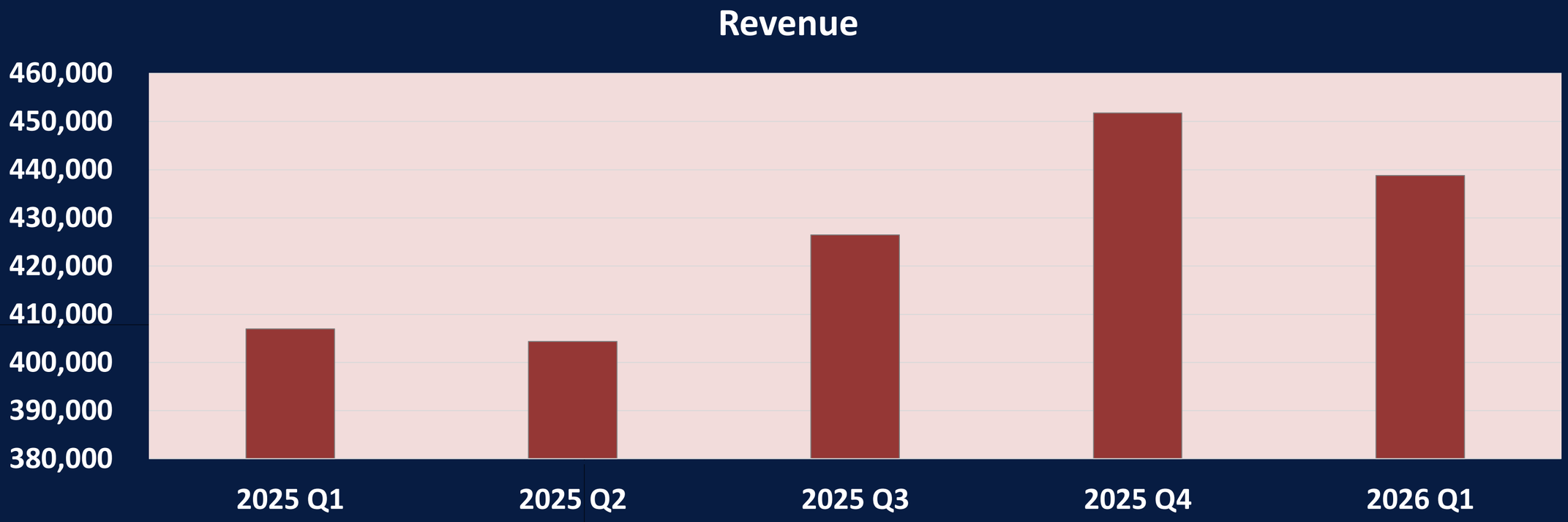
Annual Consolidated Income Statement

In NT$ Thousands	2025	2024	YoY%
Net Sales	1,689,513	1,614,588	4.64
COGS	440,703	368,144	19.71
Gross Profit	1,248,810	1,246,444	0.19
Gross margin	73.92%	77.20%	
Operating Expense	855,527	863,302	-0.90
Operating Income	393,283	383,142	2.65
Operation Margin	23.28%	23.73%	
Non-Op Inc/(Exp)	11,451	41,609	-72.48
Income before Tax	404,734	424,751	-4.71
Net Income	303,849	336,539	-9.71
Net Margin	17.98%	20.84%	
EPS	**6.66**	**7.37**	

Consolidated Balance Sheet Summary

Selected Items from Balance Sheet (NT$ Millions)	Q4'25		Q4'24		Q3'25	
	Amount	**%**	**Amount**	**%**	**Amount**	**%**
Current Assets	**1,465.5**	88.2%	**1,465.1**	86.8%	**1,347.6**	87.0%
Fixed Assets	**90.2**	5.4%	**85.0**	5.0%	**91.7**	5.9%
Net PP&E and other assets	**106.5**	6.4%	**137.4**	8.2%	**110.1**	7.1%
Total Assets	**1,662.2**	100.0%	**1,687.5**	100.0%	**1,549.4**	100.0%
Current Liabilities	**464.2**	27.9%	**467.9**	27.7%	**465.2**	30.0%
Non Current Liabilities	**32.1**	2.0%	**46.4**	2.8%	**29.5**	1.9%
Total Liabilities	**496.3**	29.9%	**514.3**	30.5%	**494.7**	31.9%
Shareholders' Equity	**1,165.9**	70.1%	**1,173.2**	69.5%	**1,054.7**	68.1%

Revenue by Quarterly



NTD : 仟元	Q1.25	Q2.25	Q3.25	Q4.25	Q1.26
Revenue	406,978	404,349	426,441	451,745	438,822

Source Code Disclosure Fee

Customers pay for a set(s) of Insyde source code supporting a specific CRB* provided by IHV**.

Royalty Fee

Customers pay “per unit” fee to Insyde for their product shipped with Insyde’s firmware on it.

NRE (Non-Recurring Engineering) Fee

Customers pay for engineering service to complete the defined tasks in the SOW (Statement Of Work)

(NRE fee per day) * (number of working man days defined in the SOW)

Insyde’s Revenue Types

* CRB: Customer Reference Board

** IHV: Independent Hardware Vendor, ex. Intel, AMD,..., etc.

Q&A

For more information, contact :

ir@insyde.com

www.insyde.com

Back up

Total 36 BMC Chips Opportunity with New AI Rack Architecture

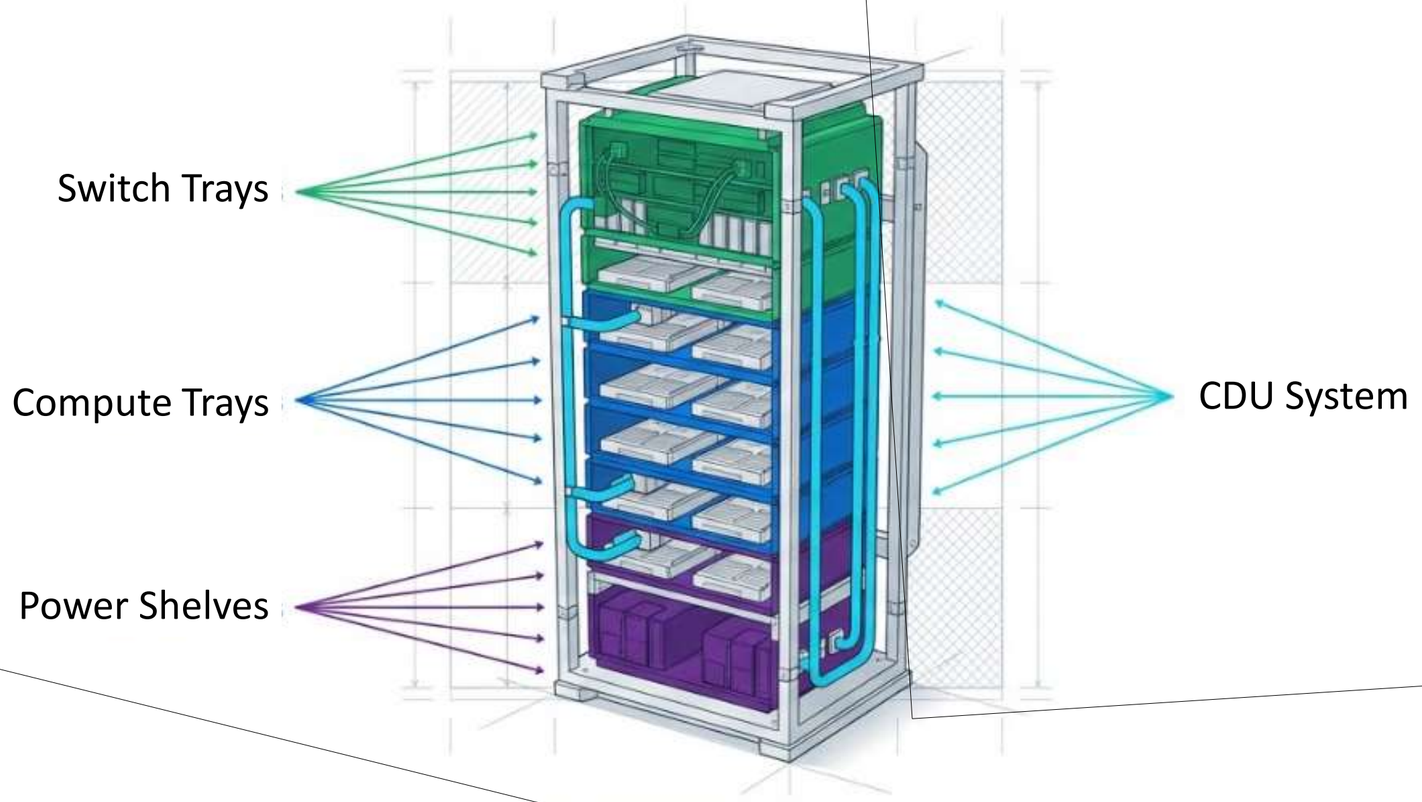
The Total Addressable Volume

18 Compute Trays
+ 9 Switch Trays
+ 8 Power Shelves
+ 1 CDU System

Anatomy of a High-Density AI Rack Design

36

One Rack. Thirty-Six Dedicated Management Points.



Insyde engineering the future AI Compute

Synology

Synology RS2825RP+, DS1825xs+,
DS1825+, DS1525+, DS925+, DS725+

GIGA COMPUTING

NVIDIA

Gigabyte® Deskside AI Workstation

GIGABYTE™

AMD EPYC

NVIDIA

Gigabyte® Rack Server (XV23-Zx0-AAJ1)

Investor Questions

2025/12/19

1.【關於 AI 伺服器與市佔率佈局】

針對 NVIDIA 新世代平台的滲透率： 隨著 AI 伺服器架構轉向異質運算（如 NVIDIA Grace CPU 採用 Arm 架構），請問系微是否因具備 Arm SystemReady 認證優勢，在 NVIDIA GB200 或後續 Rubin 平台的參考設計中，相較於傳統 x86 世代，取得了更高的市佔率或成為 ODM 的首選（First Source）？

2. OpenBMC 的商業化進展：

大型 CSP（雲端服務商）積極推動 OpenBMC 以擺脫單一供應商綁定。請問系微的 Supervyse OPF 解決方案，目前在 Tier 1 CSP 或大型 ODM（如廣達、緯穎）的導入狀況如何？這是否已成為系微切入原本由 AMI 壟斷之伺服器 BMC 市場的關鍵破口？

3.【關於競爭優勢與營收結構】

單機價值（ASP）的提升趨勢： 相較於傳統通用伺服器，AI 機櫃（如 NVL72）因架構複雜（需納入 Switch Tray 管理、更複雜的遙測 Telemetry 功能），其韌體授權金（ASP）或 NRE（委託設計費）是否呈現倍數增長？

4. 與 AMI 的競爭態勢：

面對主要競爭對手 AMI 近期的資本結構改變與轉型，系微在爭取作為 ODM 的「第二供應商（Second Source）」策略上，目前是否看到明顯的轉單效應或市佔率提升？

Investor Questions

2026/1/8

1. 關於 12 月營收的結構屬性（NRE vs. Royalty）：

12 月營收創高，請問主要驅動力是來自於新平台（如 NVIDIA GB300 或 CSP 自研晶片）的 NRE（委託設計費）入帳高峰，還是 AI 伺服器權利金（Royalty）已開始顯著堆疊？這攸關投資人如何判斷 2026 年上半年由「小量試產」轉向「大量量產」時的營收爆發斜率。

2. 針對 GB300 供應鏈版圖變化的應對：

近期供應鏈消息指出，2026 年 GB300 的主力出貨將集中於 鴻海 (Foxconn)（特別是微軟與甲骨文的訂單）。鑑於鴻海傳統上與 AMI 關係密切，請問系微是否已透過 Arm 架構 (Grace CPU) 或 OpenBMC 的技術優勢，成功切入鴻海的 GB300 供應鏈，取得合格供應商 (AVL) 資格？

3. ASIC (自研晶片) 市場的 NRE 成長性：

觀察到大型 CSP（如 Google、AWS）在 2026 年似乎將資源轉向自研 ASIC 伺服器。這類客製化專案通常需要更深度的韌體客製服務，請問公司是否觀察到來自 ASIC 專案的 NRE 需求正呈現倍數增長？這是否將成為公司 2026 年獲利的另一個隱形引擎？